

**S/N 10/774,869**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Song-Hua Shi et al.

Examiner: Douglas W. Owens

Serial No.: 10/774,869

Group Art Unit: 2811

Filed: February 9, 2004

Docket No.: 884.698US2

Title: UNDERFILL PROCESS FOR FLIP-CHIP DEVICE

Customer Number: 21186

**RESPONSE UNDER 37 CFR § 1.111**

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

This responds to the Office Action mailed on May 18, 2007. Please consider the remarks in connection with the above-identified patent application as follows.